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U.S. UTILITY Patent Application

PATENT NUMBER and ISSUE DATE

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10049875	02/12/2002	117		1765	

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**CONTINUING DATA VERIFIED:
THIS APPLICATION IS A 371 OF PCT/JP00/05738 08/25/2000

** FOREIGN APPLICATIONS VERIFIED:
JAPAN 11/241186 08/27/1999

PG-PUB	DO NOT PUBLISH ☐	RESCIND ☐	
Foreign priority claimed	☐ yes ☐ no		ATTORNEY DOCKET NO
35 USC 119 conditions met	☐ yes ☐ no		86397
Verified and Acknowledged Examiners's intials			

TITLE : Silicon wafer and method for manufacture thereof, and method for evaluation of silicon wafer

U.S.DEPT. OF COMM./PAT.& TM-PTO-436L(Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
	Assistant Examiner	Total Claims	Print Claim for O.G
ISSUE FEE		DRAWING	
Amount Due / Date Paid		Sheets Drwg. / Figs.Drwg. / Print Fig.	
☐ TERMINAL DISCLAMER	Primary Examiner	Application Examiner	
	PREPARED FOR ISSUE		

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